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TH 974
Silicone Thermal Adhesive

Description

TH 974 is a white, highly filled silicone system suitable for screen printing process and thermal dissipation of electronic devices. This one part system designed to be heat cured. It has stable pot life and long shelf life even at room temperature of 25ºC. It has relatively low viscosity for faster dispense from syringes.

Applications

1. Heat dissipation from electronic components.

Guidelines for Use

1. Thaw the silicone to room temperature (25ºC) before use.
2. Dispense the silicone by using a syringe.
3. Wipe off any excess uncured adhesive with a piece of dry cloth or tissue. Further cleaning may be achieved with tissue dabbed with isopropanol.
4. Cure the silicone by heating in a convection oven at 170ºC for 10 minutes. Curing at lower temperature will require a longer time.

Properties

Property	Test Method	Unit	Typical Value
Appearance	PEN 10	-	White
Viscosity, Brookfield CAP2000+, 25ºC	PEN 44	cP	60,000
Adhesion strength	PEN 42	kg/cm²	39.7
Pot life, 25ºC	PEN 57	Days	30
Thermal Conductivity	ASTM D5470	W/mK	2.8
Specific gravity	PEN 14	-	1.7
Hardness	PEN 29	Shore A	65
Tensile strength	PEN 41	kgf/cm^2	36
Elongation at break	PEN 41	%	57

Recommended Cure

Alternative cure	Temp. (ºC)	Cure time
A	120	60 min
B	150	30 min
C	170	10 min

Storage

Tightly close original container of unused product. Storing at lower temperatures down to -20ºC may prolong shelf life beyond 6 months. However it may take longer time to thaw the product.

Packaging

- 30ml EFD syringe
- 500g plastic jar
- 1.5kg plastic pail

Environment, Health & Safety

This product is RoHS compliant. It does not contain any known carcinogenic, mutagenic or teratogenic components.

Contact Information

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